IN THE CLAIMS:

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1. (Currently Amended) A fault detecting method for a semiconductor integrated circuit, characterized in that:

providing a fault list corresponding to (a) information en identifying physical sites of a semiconductor integrated circuit where a possible fault is likely to occur or (b) information required to reduce faults; and is used to perform detection for detecting faults in said a semiconductor integrated circuit to which said fault list corresponds by using said fault list.

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2. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 1, wherein in fault detection, faults that are difficult to detect are omitted from the fault list before detection is performed for faults in the semiconductor integrated circuit using a remaining part of the fault list additionally comprising:

omitting possible faults that are difficult to detect from the fault list to define a remaining part of the fault list, and

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detecting faults in said semiconductor integrated circuit by using the remaining part of the fault list.

- 3. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 1, wherein the fault list—contains—comprises data—on—about a likelihood of each—a fault occurring at a site.
- 4. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 3, wherein detection is performed for faults in the semiconductor integrated circuit using a fault list ordered with the likelihood of each faultadditionally comprising:

ordering the possible faults in the fault list according to their likelihood of occurrence to create an ordered fault list, and

detecting faults in said semiconductor integrated circuit
by using the ordered fault list.

5. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 3,—wherein the additionally comprising weighting possible faults—are weighted with at sites according to their likelihood to determine achieve a specific fault coverage, thereby creating weighted possible faults, said fault coverage being a probability of detecting faults in said semiconductor integrated circuit, detecting faults using a fault list comprising said weighted possible faults—for a fault detection.

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- 6. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 5, additionally comprising ordering possible wherein the faults before weighting possible faultsare ordered with their likelihood and are weighted in accordance with this ordering.
- 7. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 4, additionally comprising obtaining mask information from a layout device for laying out the semiconductor integrated circuit to



which the fault list corresponds, wherein faults are ordered or weighted with their likelihood

said ordering possible faults is based on the mask information obtained from a layout device for laying out the semiconductor integrated circuit.

8. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 4, wherein further comprising:

calculating a density of a mask pattern is calculated based

on— corresponding to mask information obtained from the a layout

device for laying out the semiconductor integrated circuit to

which said fault list corresponds;

depending on the density of the mask pattern; and

their likelihoods of occurrence are ordered or weighted with their likelihood depending on the density of the mask pattern.

9. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 4, wherein additionally comprising: the faults are ordered or weighted with their likelihood using

providing a database for storing therein reliability data based on records of past use of cells or functional blocks of the semiconductor integrated circuit to which the fault list corresponds; and

ordering the possible faults according to their likelihoods of occurrence, using the database.

10. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 6, wherein a fault coverage that can be obtained when detecting each fault is calculated and faults that are not required to achieve a specified fault coverage are deleted in the order of the unlikelihood of the faults, and detecting process is conducted for the remaining faults additionally comprising:

defining a required fault list by deleting from the fault list possible faults that are not required to achieve a

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specified fault coverage, in an order of unlikelihood of such possible faults, said specific fault coverage being a probability of detecting faults in the semiconductor integrated circuit to which said fault list corresponds; and detecting, using said required fault list, remaining faults in said semiconductor integrated circuit; and calculating a fault coverage simultaneously with said detecting.

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11. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 6, wherein additionally comprising:

calculating the fault coverage is calculated while carrying out a process for simultaneously with detecting possible faults in said semiconductor integrated circuit; and each fault detection in accordance with the ordering, and the process is stopped

specified fault coverage has been reached, said specific fault

coverage being a probability of detecting faults in said semiconductor integrated circuit.

(Currently Amended) A fault detecting method for a semiconductor integrated ci#cuit, characterized in thatcomprising:

detection is performed for first detecting faults in a semiconductor integrated circuit to create a fault listdetection result; corresponding to

combining said detection result with (a) information on about physical sites of in/the semiconductor integrated circuit to which said fault list corresponds where a possible fault is likely to occur or (b) information required to reduce faults, to create a fault list; and so that this fault list can be used to perform detection for

using said fault list for second detecting faults in said semiconductor integrated circuit.

13. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 12, wherein in fault detection, faults that are difficult to detect are omitted from a fault list before detection is performed for faults in the semiconductor integrated circuit using a remaining part of the fault listadditionally comprising:

omitting from the fault list possible faults that are difficult to detect to define a remaining part of the fault list, wherein

said second detecting faults in a semiconductor integrated circuit to which said fault list comprises using the remaining part to detect faults.

14. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 12, wherein the fault list contains comprises data on about a likelihood of each a possible fault occurring at a site.

15. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 14, wherein detection is performed for faults in the semiconductor integrated circuit using a fault list ordered with the likelihood of each faultadditionally comprising:

ordering the possible faults according to their likelihood of occurrence to create an ordered fault list, and

second detecting possible faults in said semiconductor integrated circuit using the ordered fault.

semiconductor integrated circuit according to claim 14,—wherein the—additionally comprising weighting possible faults are weighted with at sites according to their likelihood to determine—achieve a specific fault coverage, thereby creating weighted possible faults, said fault coverage being a probability of detecting faults in said semiconductor integrated circuit, and for a fault detection

second detecting faults using a fault list comprising said weighted possible faults.

17. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 16, wherein the additionally comprising ordering possible faults before weighting possible faults are ordered with their likelihood and are weighted in accordance with this ordering.

18. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 15, additionally comprising obtaining mask information from a layout device for laying out the semiconductor integrated circuit to which the fault list corresponds, wherein the faults are ordered or weighted with their likelihood

said ordering possible faults is based on the mask information obtained from a layout device for laying out the semiconductor integrated circuit.

19. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 15, wherein further comprising

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Serial No.: 09/697,305

calculating a density of a mask pattern is calculated based on corresponding to mask information obtained from the a layout device for laying out the semiconductor integrated circuit to which said fault list corresponds; and the faults are ordered or weighted with

depending on the density of the mask pattern; and

ordering or weighting the possible faults according to their likelihood likelihoods of occurrence depending on the density of the mask pattern.

20. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 15, wherein further comprising: the faults are ordered or weighted with their likelihood using

providing a database for and storing therein reliability data based on records of past use of cells or functional blocks of the semiconductor integrated circuit to which the fault list corresponds; and



ordering the possible faults according to their likelihoods
of occurrence, using the database.

21. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 17, wherein a fault coverage that can be obtained when detecting each fault is calculated and faults that are not required to achieve a specified fault coverage are deleted in the order of the unlikelihood of the faults, and detecting process is conducted for the remaining faults additionally comprising:

defining a required fault list by deleting from the fault list possible faults that are not required to achieve a specified fault coverage in an order of unlikelihood of such possible faults, said specific fault coverage being a probability of detecting faults in the semiconductor integrated circuit to which said fault list corresponds; and

second detecting using said required fault list, remaining possible faults in said semiconductor integrated circuit; and calculating a fault coverage simultaneously with said second detecting.

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22. (Currently Amended) The fault detecting method for a semiconductor integrated circuit according to claim 17, additionally comprising: wherein the

calculating the fault coverage simultaneously with detecting possible faults in said semiconductor integrated circuit; and

terminating calculating and detecting is calculated while carrying out a process for each fault detection in accordance with the ordering, and the process is stoppedonce the when a specific specified fault coverage has been reached, said specific fault coverage being a probability of detecting faults in said semiconductor integrated circuit.

23. (Withdrawn) A layout method for a semiconductor integrated circuit, characterized in that:

a fault list corresponding to information on sites of a semiconductor integrated circuit where a fault is likely to occur or information required to reduce faults is used to

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perform mask layout and wiring for said semiconductor integrated circuit.

- 24. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 23, wherein the fault list contains data on likelihood of each fault.
- 25. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 24, wherein the mask layout and the wiring are performed for the semiconductor integrated circuit using a fault list ordered with the likelihood of each fault.
- 26. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 24, wherein the faults are weighted with their likelihood to determine a fault coverage for the mask layout and wiring for the semiconductor integrated circuit.

- 27. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 26, wherein the faults are ordered with their likelihood and are weighted in accordance with this ordering.
- 28. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 25, wherein the faults are ordered or weighted with their likelihood based on mask information obtained from a layout device for laying out the semiconductor integrated circuit.

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29. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 25, wherein a density of a mask pattern is calculated based on mask information obtained from the layout device for laying out the semiconductor integrated circuit, and the faults are ordered or weighted with their likelihood depending on the density of the mask pattern.

- 30. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 25, wherein the faults are ordered or weighted with their likelihood using a database for reliability based on records of past use of cells or functional blocks of the semiconductor integrated circuit.
 - 31. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 27, wherein a fault coverage that can be obtained when detecting each fault is calculated, faults that are not required to achieve a specified fault coverage are deleted in the order of the unlikelihood of the faults, and detecting process is conducted for the remaining faults.
 - 32. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 27, wherein the fault coverage is calculated while carrying out a process for each fault detection in accordance with the ordering, and the process is stopped once the specified fault coverage has been reached.

33. (Withdrawn) A layout method for a semiconductor integrated circuit, characterized in that:

detection is performed for faults in a semiconductor integrated circuit to create a fault list indicating information on sites of a semiconductor where a fault is likely to occur or information required to reduce faults so that this fault list can be used to perform mask layout and wiring for said semiconductor integrated circuit.

- 34. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 33, wherein the fault list contains data on likelihood of each fault.
- 35. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 34, wherein the mask layout and the wiring are performed for the semiconductor integrated circuit using a fault list ordered with the likelihood of each fault.

- 36. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 34, wherein the faults are weighted with their likelihood to determine a fault coverage for the mask layout and wiring for the semiconductor integrated circuit.
- 37. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 36, wherein the faults are ordered with their likelihood and are weighted in accordance with this ordering.
- 38. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 35, wherein the faults are ordered or weighted with their likelihood based on mask information obtained from a layout device for laying out the semiconductor integrated circuit.
- 39. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 35, wherein a density of a mask pattern is calculated based on mask information obtained

from the layout device for laying out the semiconductor integrated circuit, and the faults are ordered or weighted with their likelihood depending on the density of the mask pattern.

- 40. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 35, wherein the faults are ordered or weighted with their likelihood using a database for reliability based on records of past use of cells or functional blocks of the semiconductor integrated circuit.
- 41. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 37, wherein a fault coverage that can be obtained when detecting each fault is calculated, faults that are not required to achieve a specified fault coverage are deleted in the order of the unlikelihood of the faults, and detecting process is conducted for the remaining faults.
- 42. (Withdrawh) The layout method for a semiconductor integrated circuit according to claim 37, wherein the fault

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coverage is calculated while carrying out a process for each fault detection in accordance with the ordering, and the process is stopped once the specified fault coverage has been reached.

43. (Withdrawn) A layout method for a semiconductor integrated circuit, characterized in that:

faults that are difficult to detect are omitted from a fault list before mask layout and wiring are performed based on the remaining part of the fault list for the semiconductor integrated circuit.

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- 44. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 43, wherein the fault list contains data on likelihood of each fault.
- 45. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 44, wherein the mask layout and the wiring are performed for the semiconductor integrated circuit using a fault list ordered with the likelihood of each fault.

- 46. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 44, wherein the faults are weighted with their likelihood to determine a fault coverage for the mask layout and wiring for the semiconductor integrated circuit.
- 47. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 46, wherein the faults are ordered with their likelihood and are weighted in accordance with this ordering.
- 48. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 45, wherein the faults are ordered or weighted with their likelihood based on mask information obtained from a layout device for laying out the semiconductor integrated circuit.
- 49. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 45, wherein a density of a

mask pattern is calculated based on mask information obtained from the layout device for laying out the semiconductor integrated circuit, and the faults are ordered or weighted with their likelihood depending on the density of the mask pattern.

- 50. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 45, wherein the faults are ordered or weighted with their likelihood using a database for reliability based on records of past use of cells or functional blocks of the semiconductor integrated circuit.
- 51. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 47, wherein a fault coverage that can be obtained when detecting each fault is calculated, faults that are not required to achieve a specified fault coverage are deleted in the order of the unlikelihood of the faults, and detecting process is conducted for the remaining faults.

52. (Withdrawn) The layout method for a semiconductor integrated circuit according to claim 47, wherein the fault coverage is calculated while carrying out a process for each fault detection in accordance with the ordering, and the process is stopped once the specified fault coverage has been reached.